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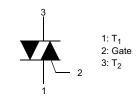


### FKN2L60

### **Application Explanation**

- Switching mode power supply, light dimmer, electric flasher unit, hair drier
- TV sets, stereo, refrigerator, washing machine
- Electric blanket, solenoid driver, small motor control
- Photo copier, electric tool





## **Bi-Directional Triode Thyristor Planar Silicon**

### **Absolute Maximum Ratings** T<sub>C</sub>=25°C unless otherwise noted

Symbol	Parameter	Rating	Units
$V_{DRM}$	Repetitive Peak Off-State Voltage (Note1)	600	V

Symbol	Parameter	Conditions		Rating	Units
I <sub>T (RMS)</sub>	RMS On-State Current	Commercial frequency, sine full wave 360° conduction, Tc=65 ℃		1.5	Α
I <sub>TSM</sub>	Surge On-State Current	Sinewave 1 full cycle, peak value, non-repetitive 50Hz		9	Α
				10	Α
l <sup>2</sup> t	I <sup>2</sup> t for Fusing	Value corresponding to 1 cycle of halfwave, surge on-state current, tp=10ms		0.4	A <sup>2</sup> s
di/dt	Critical Rate of Rise of On-State Current	I <sub>G</sub> = 2x I <sub>GT</sub> , tr ≤ 100ns		50	A/μs
P <sub>GM</sub>	Peak Gate Power Dissipation			1	W
P <sub>G (AV)</sub>	Average Gate Power Dissipation		0.1	W	
$V_{GM}$	Peak Gate Voltage		6	V	
I <sub>GM</sub>	Peak Gate Current	eak Gate Current		0.5	Α
T <sub>J</sub>	Junction Temperature			- 40 ~ 125	°C
T <sub>STG</sub>	Storage Temperature			- 40 ~ 125	°C

### **Thermal Characteristic**

Symbol	Parameter	Test Condition	Min.	Тур.	Max.	Units
R <sub>th(J-C)</sub>	Thermal Resistance	Junction to case (Note 4)	-	-	40	°C/W

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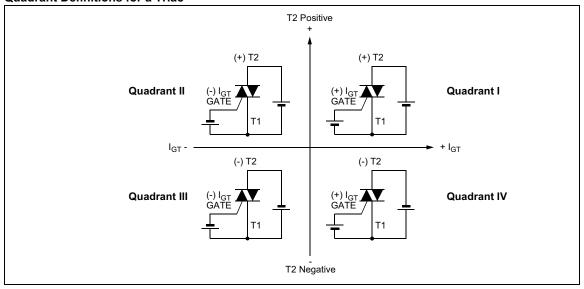
## $\textbf{Electrical Characteristics} \ \, \textbf{T}_{\text{C}} = 25^{\circ} \text{C unless otherwise noted}$

Symbol	Parameter		Test Condition		Min.	Тур.	Max.	Units
I <sub>DRM</sub>	Repetieive Peak Off-State Current		V <sub>DRM</sub> applied		-	-	20	μΑ
V <sub>TM</sub>	On-State Voltage		T <sub>C</sub> =25°C, I <sub>TM</sub> =3A Instantaneous measurement		-	-	1.6	V
	41.4.0	I		T2(+), Gate (+)	-	-	1.5	V
$V_{GT}$	Gate Trigger Voltage (Note 2)	II	$V_D$ =12V, $R_L$ =20 $\Omega$	T2(+), Gate (-)	-	-	1.5	V
		III		T2(-), Gate (-)	-	-	1.5	V
		I		T2(+), Gate (+)	-	-	5	mA
$I_{GT}$	Gate Trigger Current (Note 2)	II	$V_D$ =12V, $R_L$ =20 $\Omega$	T2(+), Gate (-)	-	-	5	mA
		III		T2(-), Gate (-)	-	-	5	mA
V <sub>GD</sub>	Gate Non-Trigger Voltage		T <sub>J</sub> =125°C, V <sub>D</sub> =1/2V <sub>DRM</sub>		0.2	-	-	V
I <sub>H</sub>	Holding Current		V <sub>D</sub> = 12V, I <sub>TM</sub> = 1A		-	-	10	mA
IL	Latching Current	I, III	$V_D = 12V, I_G = 1.2I_{GT}$		-	-	10	mA
		II			-	-	10	mA
dv/dt	Critical Rate of Rise of Off-State Voltag		$V_{DRM}$ = Rated, $T_j$ = 125°C, Exponential Rise		500	-	-	V/µs
(dv/dt) <sub>C</sub>	Critical-Rate of Rise of Off-State Commutating Voltage (Note 3)				5	-	-	V/µs

- Notes:
  1. Gate Open
  2. Measurement using the gate trigger characteristics measurement circuit
  3. The critical-rate of rise of the off-state commutating voltage is shown in the table below
  4. Case temperature is measured at the T2 terminal 1.5mm away from the molded case.

V <sub>DRM</sub> (V)	Test Condition	Commutating voltage and current waveforms (inductive load)
FKN2L60	1. Junction Temperature  T <sub>J</sub> =125°C  2. Rate of decay of on-state commutating current  (di/dt) <sub>C</sub> = - 0.5A/ms  3. Peak off-state voltage  V <sub>D</sub> = 400V	Supply Voltage  Main Current  Main Voltage  (dv/dt)  Time

#### **Quadrant Definitions for a Triac**



# **Typical Curves**

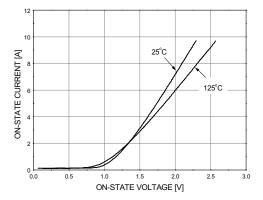


Figure 1. Maximum On-state Characteristics

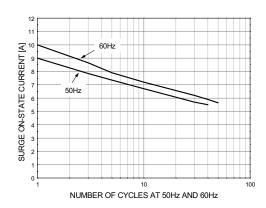


Figure 2. Rated Surge On-state Current

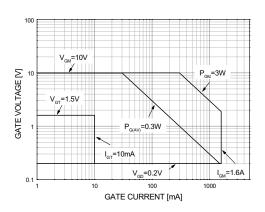


Figure 3. Gate Characteristics

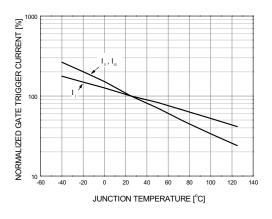


Figure 4. Gate Trigger Current vs Tj

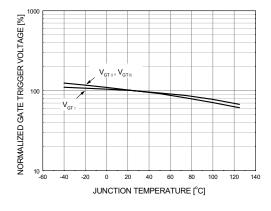


Figure 5. Gate Trigger Voltage vs Tj

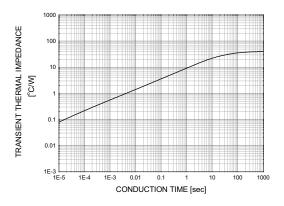


Figure 6. Transient Thermal Impedance

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## Typical Curves (Continues)

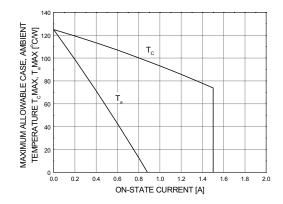


Figure 7. Allowable Case, Ambient Temperature vs Rms On-state Current

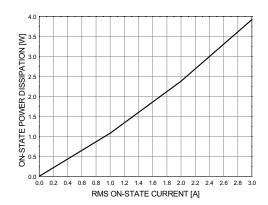


Figure 8. Maximum On-state Power Dissipation

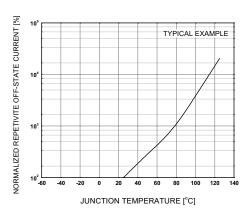


Figure 9. Repetitive Peak Off-state Current vs Junction Temperature

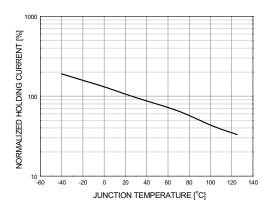


Figure 10. Holding Current vs
Junction Temperature

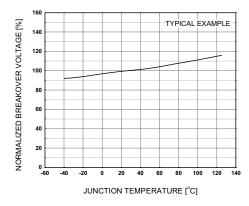


Figure 11. Breakover Voltage vs Junction Temperature

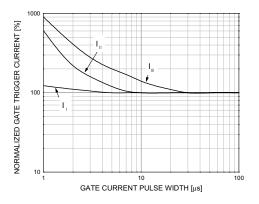


Figure 12. Gate Trigger Current vs
Gate Current Pulse Width

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# Typical Curves (Continues)

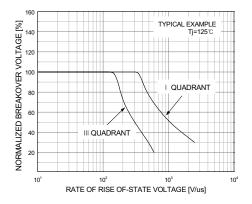
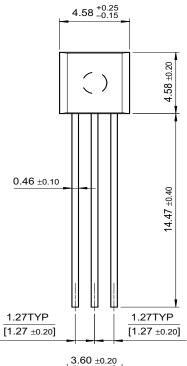


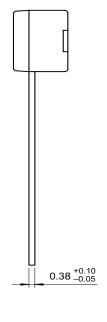
Figure 13. Breakover Voltage vs Rate of Rise of Off-state Voltage

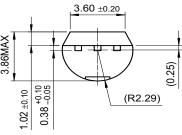
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# **Package Dimension**

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DOME™	GlobalOptoisolator™	MicroPak™	QFET®	SuperSOT™-8
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